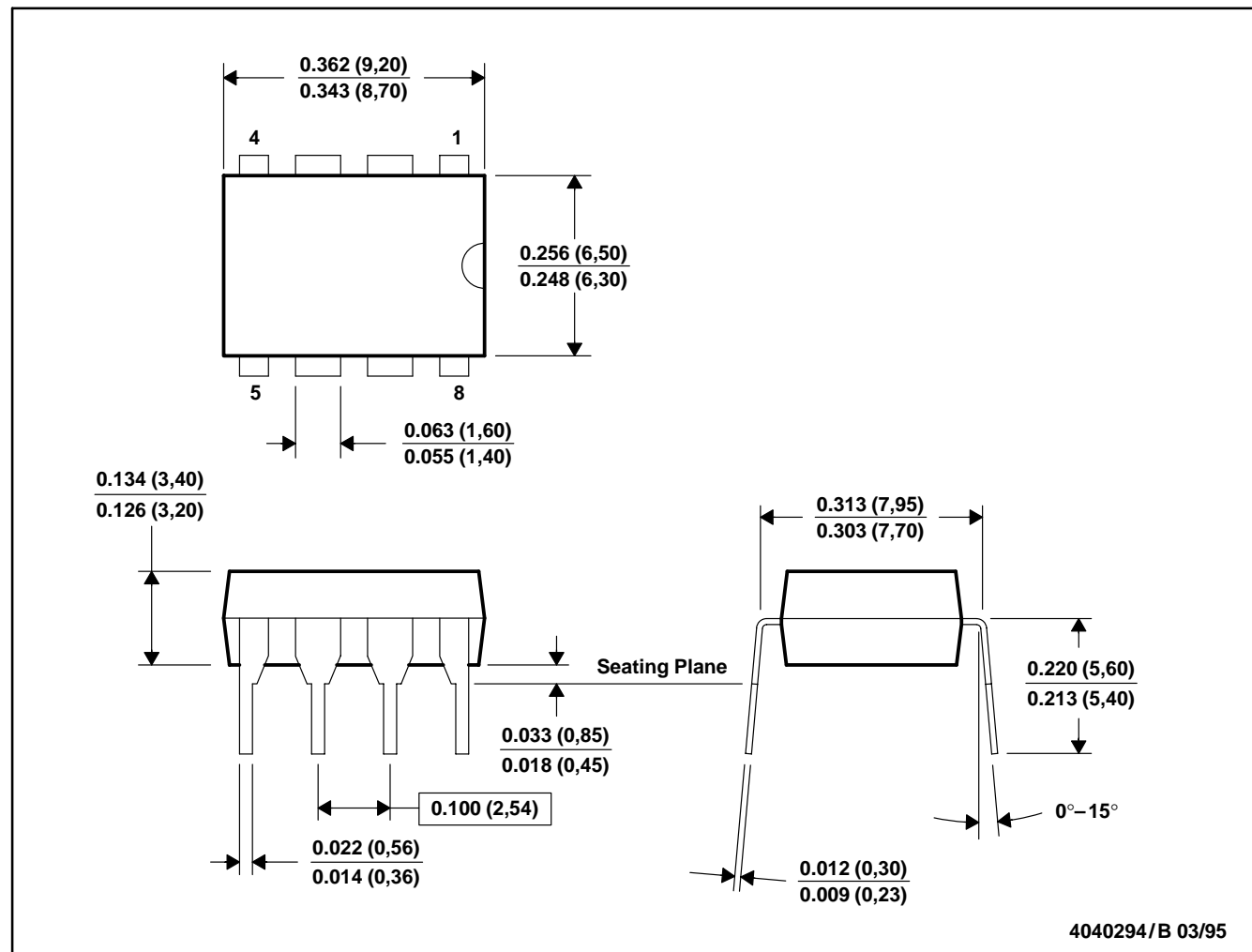


NU (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE (OPTO)



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - All dimensions apply before solder dip.
 - Package body is a clear non-filled optically transparent material.
 - Optical center is determined by lead frame design.

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